

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- Green Device Available

Product Summary



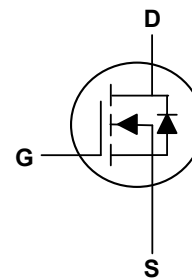
V_{DS}	110	V
I_D	3	A
$R_{DS(ON)}$ (at $V_{GS}=10V$)	230	m Ω

Applications

- High Frequency Point-of-Load, Synchronous Buck Converter
- Networking DC-DC Power System
- Load Switch



SOT23-6L Top View



Absolute Maximum Ratings($T_A=25^{\circ}C$, unless otherwise noted)

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V_{DS}	110	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current	I_D	3	A
Pulsed Drain Current ²	I_{DM}	10	A
Total Power Dissipation ³	P_D	1.25	W
Storage Temperature Range	T_{STG}	-55 to 150	$^{\circ}C$
Operating Junction Temperature Range	T_J	-55 to 150	$^{\circ}C$

Thermal Characteristics

Parameter	Symbol	Typ	Max	Unit
Thermal Resistance Junction-Ambient ¹	$R_{\theta JA}$	---	62.5	$^{\circ}C/W$

Electrical Characteristics ($T_J=25^{\circ}\text{C}$, unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V$, $I_D=250\mu A$	110	---	---	V
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=10V$, $I_D=1A$	---	200	230	$m\Omega$
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}$, $I_D=250\mu A$	1.2	---	2.5	V
Drain-Source Leakage Current	I_{DSS}	$V_{DS}=110V$, $V_{GS}=0V$, $T_A=25^{\circ}\text{C}$	---	---	1	μA
Gate-Source Leakage Current	I_{GSS}	$V_{GS}=\pm 20V$, $V_{DS}=0V$	---	---	± 100	nA
Forward Transconductance	g_{fs}	$V_{DS}=5V$, $I_D=1A$	1	---	---	S
Total Gate Charge	Q_g	$V_{DS}=50V$, $V_{GS}=10V$, $I_D=1.3A$	---	5.2	---	nC
Gate-Source Charge	Q_{gs}		---	0.75	---	
Gate-Drain Charge	Q_{gd}		---	1.4	---	
Turn-On Delay Time	$T_{d(on)}$	$V_{DD}=50V$, $V_{GS}=10V$, $R_G=1\Omega$, $I_D=1.3A$, $R_L=39\Omega$	---	6	---	ns
Rise Time	T_r		---	10	---	
Turn-Off Delay Time	$T_{d(off)}$		---	10	---	
Fall Time	T_f		---	6	---	
Input Capacitance	C_{iss}	$V_{DS}=50V$, $V_{GS}=0V$, $f=1\text{MHz}$	---	190	---	pF
Output Capacitance	C_{oss}		---	22	---	
Reverse Transfer Capacitance	C_{rss}		---	13	---	

Drain-Source Diode Characteristics

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Continuous Source Current ¹	I_S	$T_A=25^{\circ}\text{C}$	---	---	2	A
Diode Forward Voltage ²	V_{SD}	$V_{GS}=0V$, $I_S=1A$, $T_J=25^{\circ}\text{C}$	---	---	1.2	V

Note:

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
2. The data tested by pulsed, pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
3. The power dissipation is limited by 150°C junction temperature

Typical Characteristics

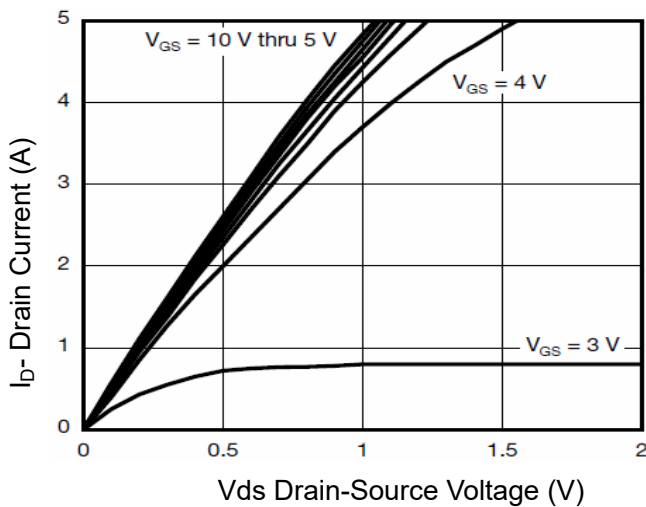


Figure 1 Output Characteristics

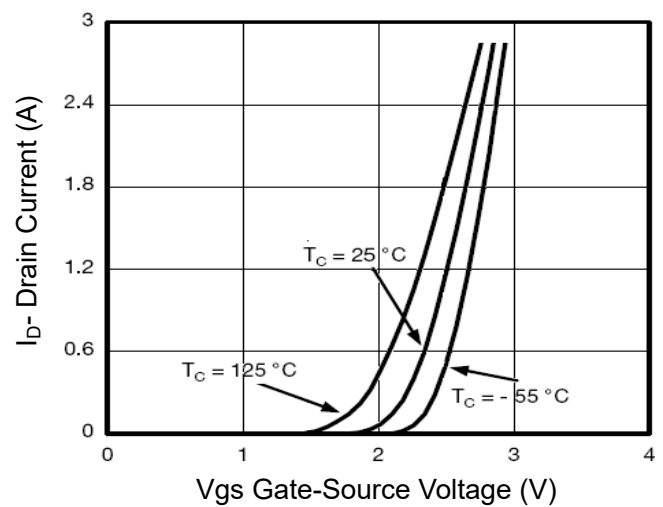


Figure 2 Transfer Characteristics

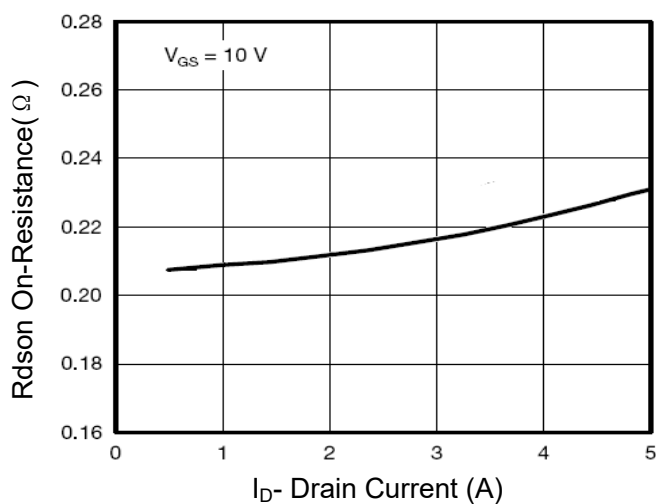


Figure 3 $R_{DS(on)}$ - Drain Current

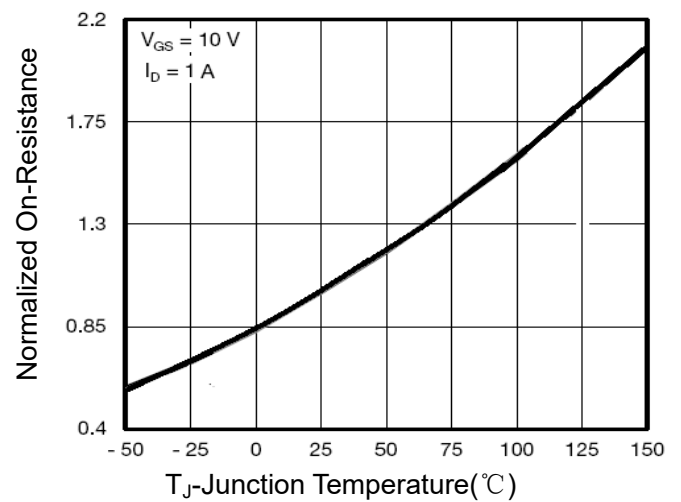


Figure 4 $R_{DS(on)}$ -Junction Temperature

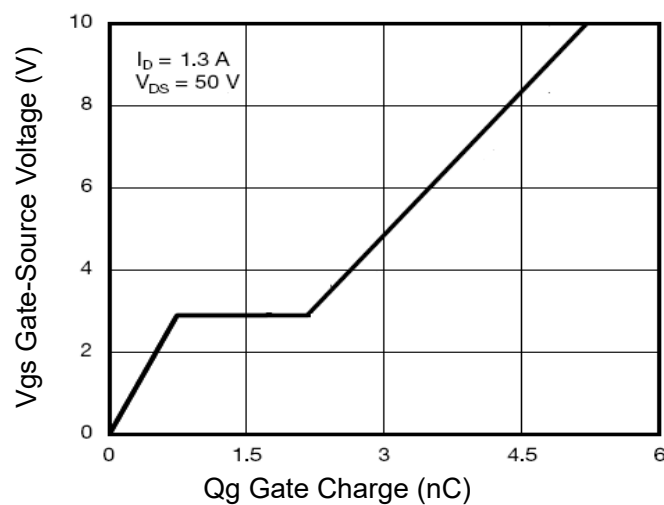


Figure 5 Gate Charge

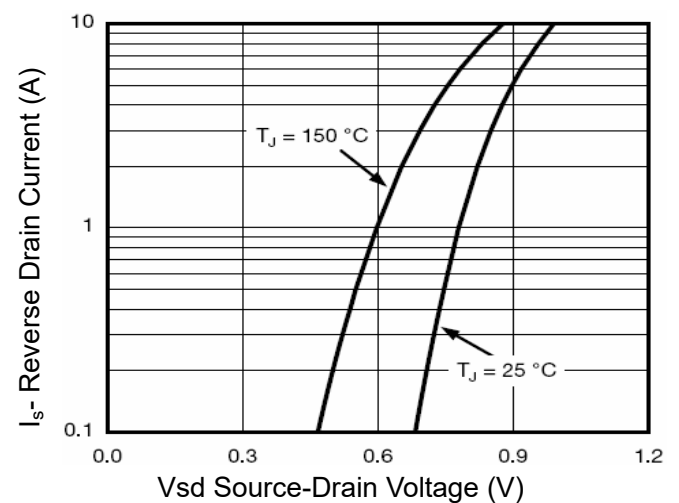


Figure 6 Source- Drain Diode Forward

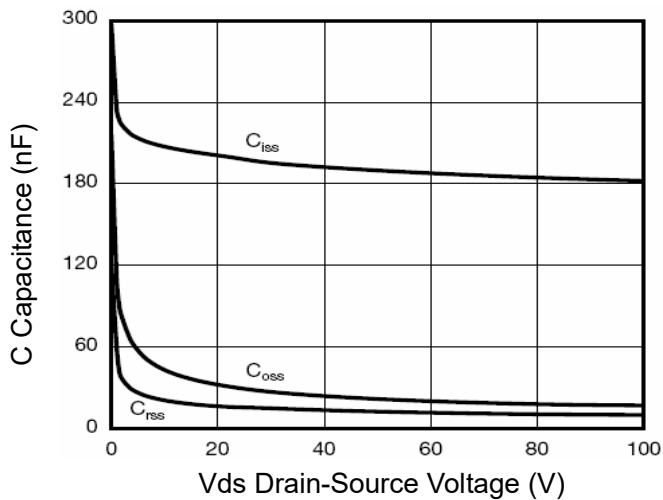


Figure 7 Capacitance vs Vds

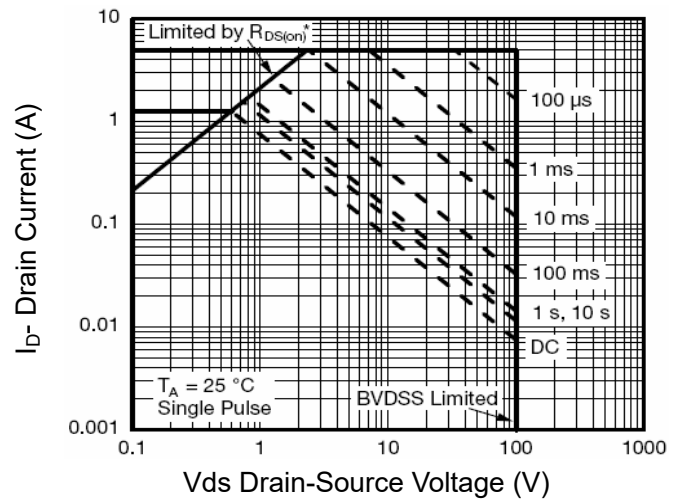


Figure 8 Safe Operation Area

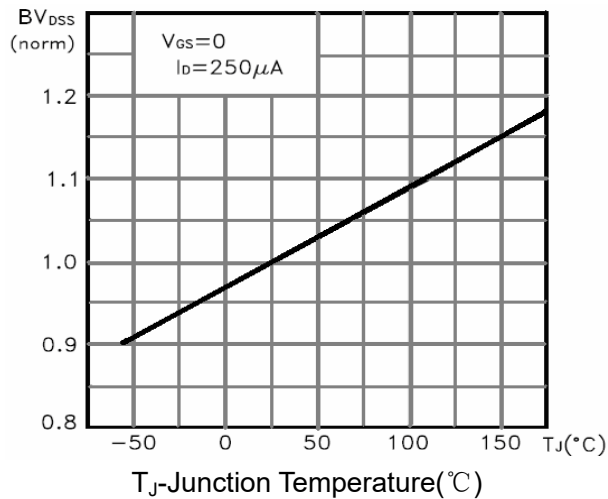


Figure 9 BV_{DS} vs Junction Temperature

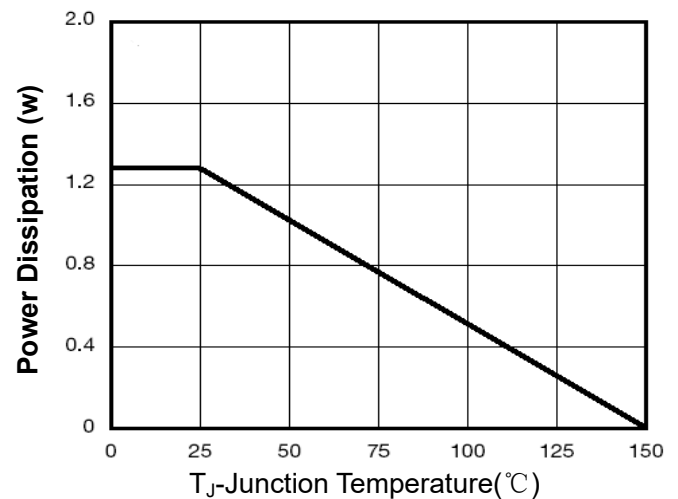


Figure 10 Power De-ratin

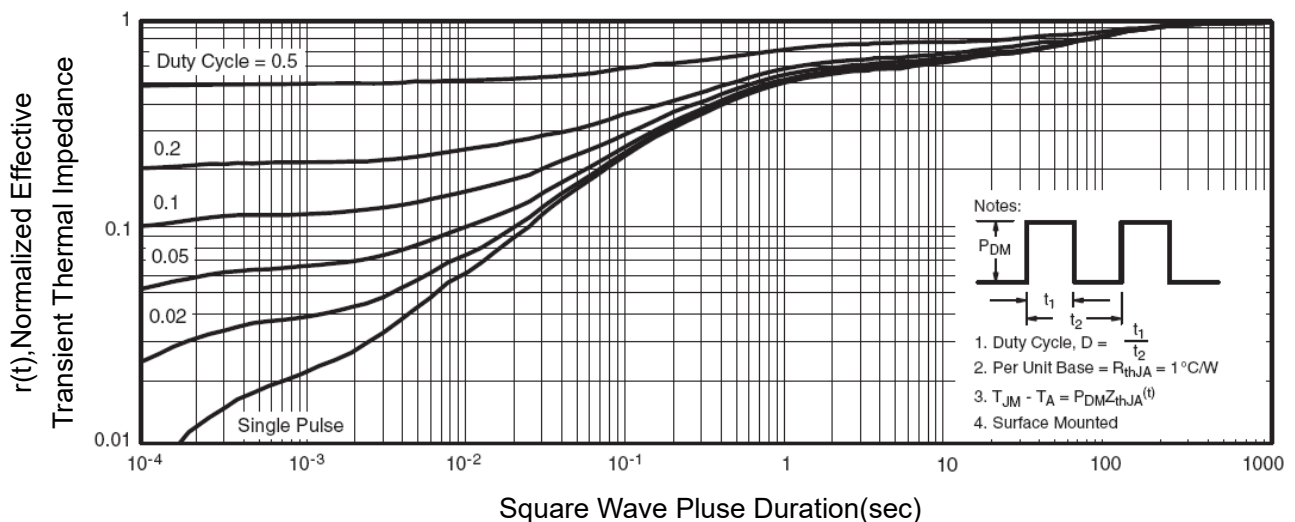
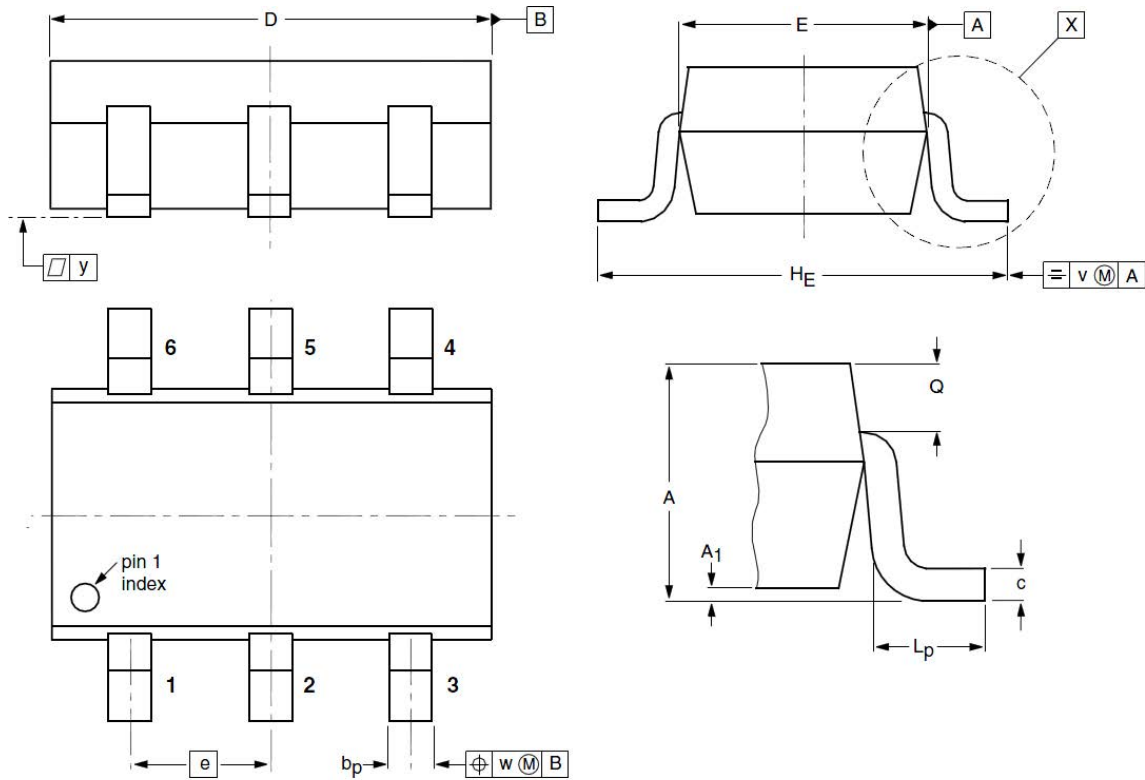


Figure 11 Normalized Maximum Transient Thermal Impedance

SOT23-6L Package Outline Dimensions



Symbol	Dimensions (unit:mm)			Symbol	Dimensions (unit:mm)		
	Min	Typ	Max		Min	Typ	Max
A	0.90	1.07	1.45	A₁	0.01	0.05	0.15
b_p	0.30	0.40	0.50	c	0.10	0.15	0.22
D	2.70	2.92	3.10	E	1.35	1.55	1.75
e	--	0.95	--	H_E	2.50	2.80	3.00
L_p	0.30	0.45	0.60	Q	0.23	0.29	0.33
v	--	0.20	--	W	--	0.20	--
y	--	0.10	--				